





SURFACE MOUNT SWITCHING DIODE ARRAY

Features

- Fast Switching Speed
- Low Capacitance
- Low Leakage Current
- Two "BAV70" Circuits in One Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (BAV70HDWQ)

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe
 (Lead-Free Plating). Solderable per MIL-STD-202, Method 208@3
- Orientation: See Diagram
- Weight: 0.006 grams (Approximate)

SOT363



Top View



Top View Internal Schematic

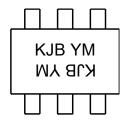
Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging		
BAV70HDW-7	AEC-Q101	SOT363	3,000/Tape & Reel		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



KJB = Product Type Marking Code YM = Date Code Marking Y = Year ex: E = 2017 M = Month ex: 9 = September

Date Code Key

	Year	2015		2016	2017		2018	2019)	2020	2021		2022
	Code	С		D	Е		F	G		Н	- [J
ſ	Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
ſ	Code	1	2	2	1	5	6	7	Q	0	0	N	ם



Maximum Ratings $(@T_A = +25^{\circ}C, \text{ unless otherwise specified.})$

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _R WM V _R	100	V
RMS Reverse Voltage		V _{R(RMS)}	71	V
Forward Continuous Current (Note 5)		I _{FM}	250	mA
Average Rectified Output Current (Note 5)		l ₀	125	mA
Repetitive Peak Forward Current		I _{FRM}	450	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs @ t = 1.0ms @ t = 1.0s	I _{FSM}	4 1 0.5	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	350	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ heta JA}$	357	°C/W
Thermal Resistance, Junction to Solder Point	$R_{\theta JSP}$	255	°C/W
Operating and Storage Temperature Range	T_J , T_{STG}	-65 to +150	°C

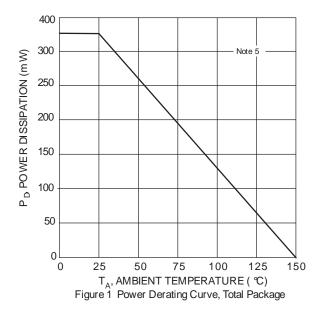
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

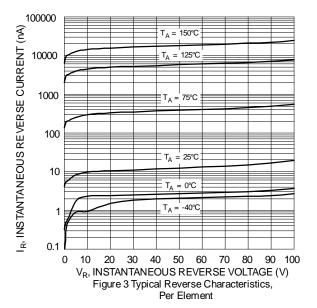
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	100	_	V	$I_R = 20\mu A$
	V _F	_	0.715	V	$I_F = 1.0 \text{mA}$
Forward Voltage			0.855		$I_F = 10mA$
l olward voltage			1.0		$I_F = 50 \text{mA}$
			1.25		I _F = 150mA
	I _R		0.5	μA	$V_R = 80V$
Reverse Current (Note 6)			100	μA	$V_R = 80V, T_J = +150$ °C
Neverse Current (Note o)			30	μA nA	$V_R = 25V, T_J = +150$ °C
			30		$V_R = 25V$
Total Capacitance	C _T	_	1.5	pF	$V_R = 0, f = 1.0MHz$
Reverse Recovery Time	+		4.0		$I_F = I_R = 10 \text{mA},$
Neverse Necovery Time	t _{RR}		4.0	ns	$I_{RR} = 0.1 \text{ x } I_{R}, R_{L} = 100\Omega$
Forward Recovery Voltage	V_{FR}	_	1.75	V	$I_F = 10 \text{mA}, t_R = 20 \text{ns}$

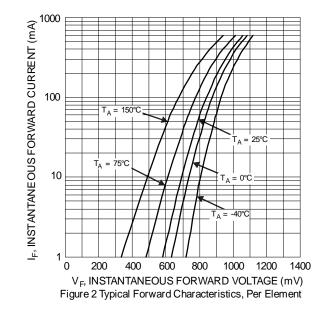
Notes: 5. Part is mounted on a FR-4 substrate PC board, with 1" x 1" 2oz Cu pad.

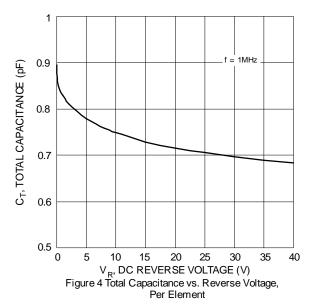
6. Short duration pulse test used to minimize self-heating effect.









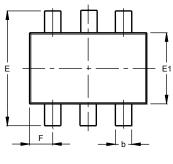


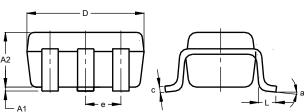


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



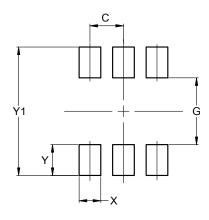


	SOT363						
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	1.00				
b	0.10	0.30	0.25				
С	0.10	0.22	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	E1 1.15		1.30				
е	().650 E	SC				
F	0.40	0.45	0.425				
L	0.25	0.40	0.30				
а	0°	8°	_				
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



Dimensions	Value		
	(in mm)		
C	0.650		
G	1.300		
X	0.420		
Υ	0.600		
V1	2.500		



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